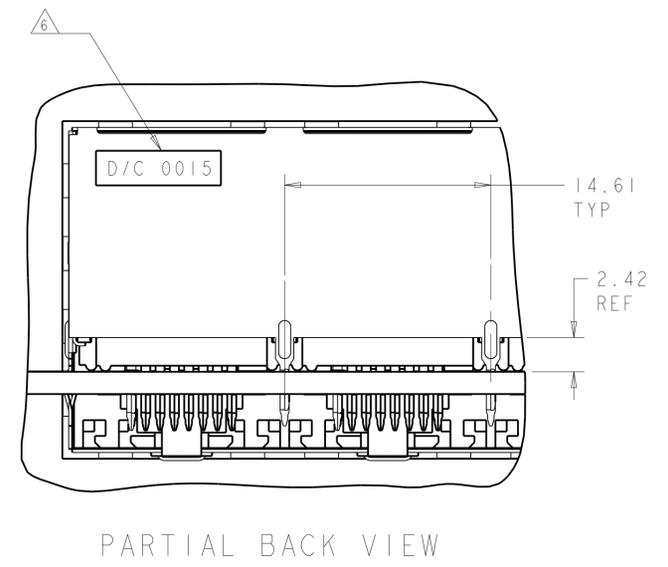
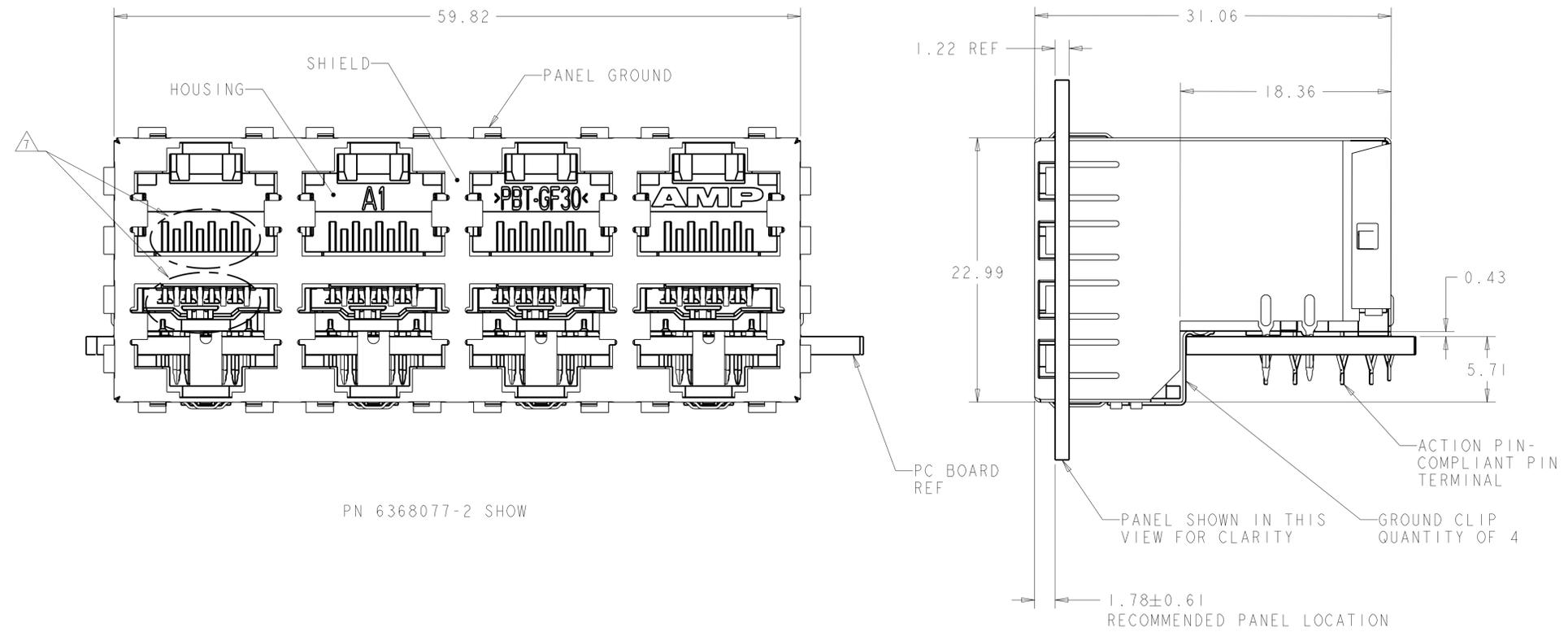


LOC		DIST		REVISIONS			
P	LTN	DESCRIPTION	DATE	DWN	APVD		
A		RELEASED PER ECOS11-0201-04	27JUL2005	DR	JW		
B		ECO-08-028011	11NOV2008	JY	SY		
C		REVISED PER ECO-21-000623	28JAN2021	AK	SZ		

- MATERIAL:
 - HOUSING
PBT POLYESTER, BLACK, UL 94V-0.
 - TERMINALS
0.30 THICK PHOSPHOR BRONZE PLATED WITH 1.27μm MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 2μm MINIMUM THICK MATTE TIN IN ACTION PIN COMPLIANT PIN TERMINAL AREA OVER 1.27μm MINIMUM THICK NICKEL UNDERPLATE.
 - SHIELD
0.25 THICK COPPER ALLOY PLATED WITH 1.27μm MINIMUM NICKEL.
 - GROUND CLIP
0.25 THICK COPPER ALLOY WITH 2.03μm MINIMUM MATTE TIN OVER 1.27μm MINIMUM NICKEL.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- ALL DIMENSIONS ARE NOMINAL UNLESS OTHERWISE SPECIFIED.
 - ④ DRILLED HOLE DIA = 1.02±.025.
COPPER THICKNESS = 0.025-0.075.
TIN THICKNESS = 0.008 MIN.
 - ⑤ DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
 - ⑥ DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN.
 - ⑦ CONTACTS ARE NOT INTENDED TO BE ALIGNED WITH EACH OTHER.



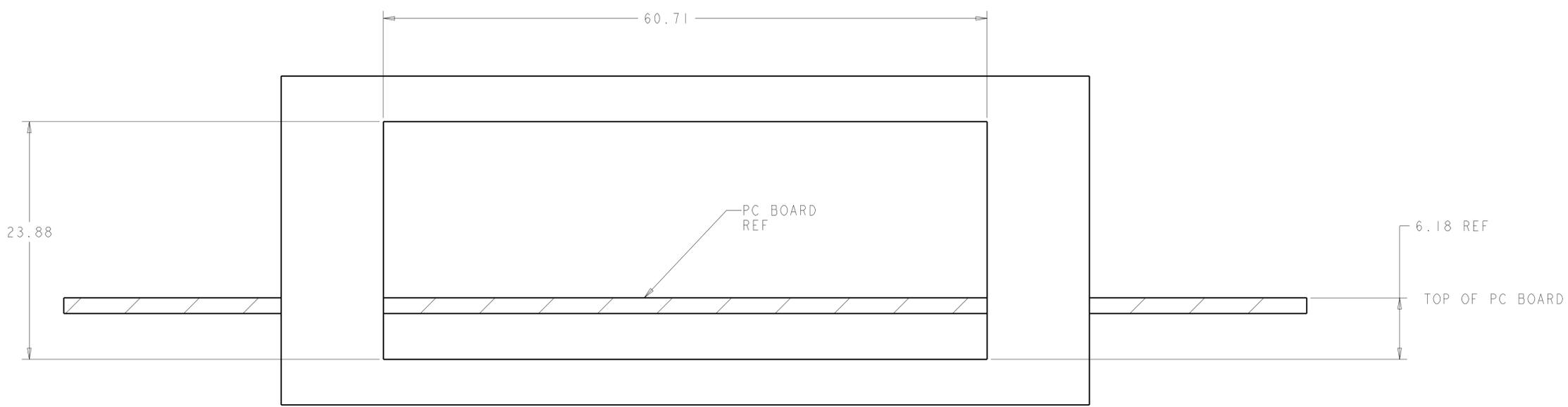
PN 6368077-2 SHOW

DESCRIPTION	PART NUMBER
WITH GROUND CLIP	6368077-2
WITHOUT GROUND CLIP	6368077-1

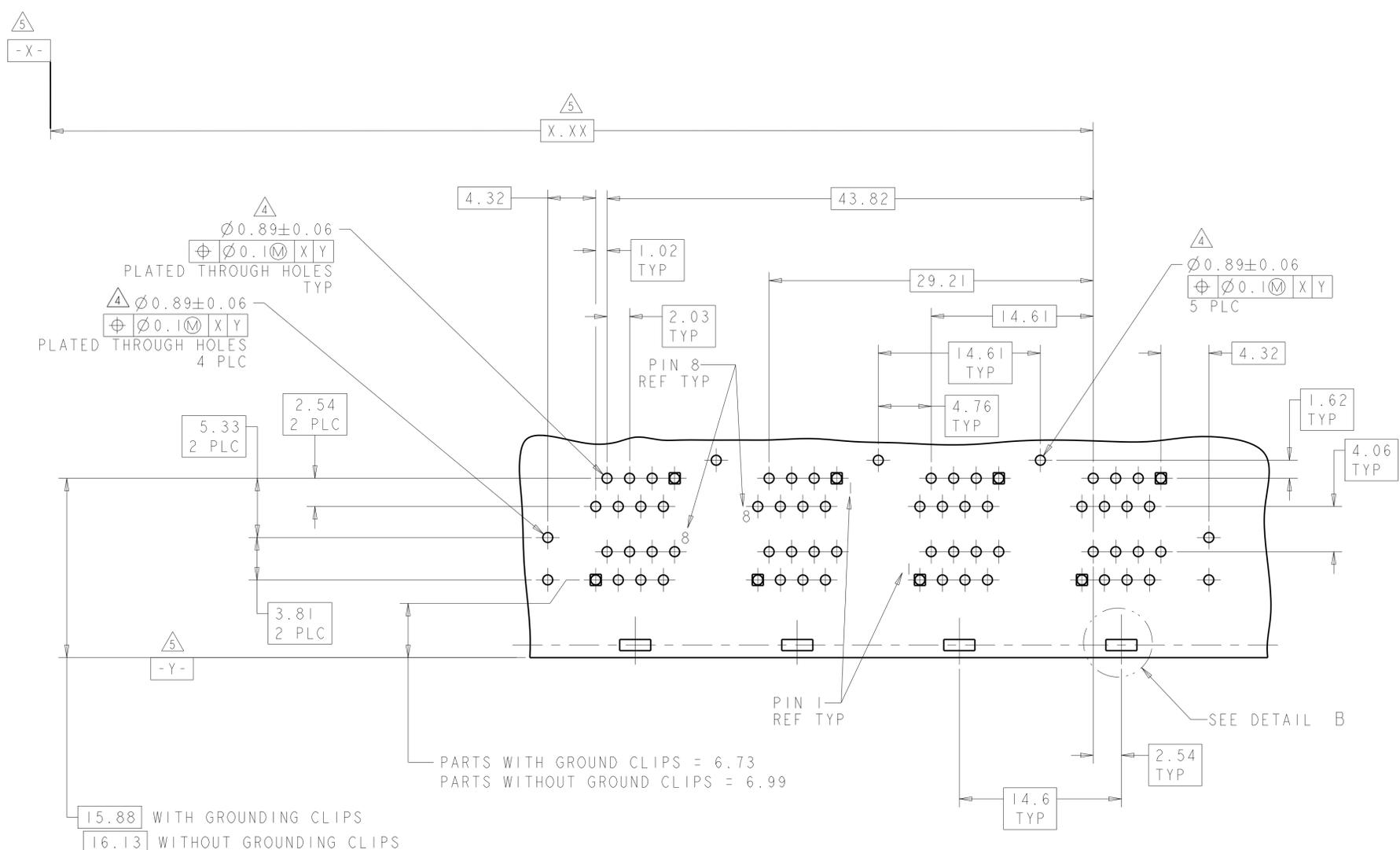
DIMENSIONS: mm 0 PLC ±.13 1 PLC ±0.13 2 PLC ±0.13 3 PLC ±.13 4 PLC ±.13 ANGLES ±.1° FINISH -		TOLERANCES UNLESS OTHERWISE SPECIFIED: DIMENSIONS: mm 0 PLC ±.13 1 PLC ±0.13 2 PLC ±0.13 3 PLC ±.13 4 PLC ±.13 ANGLES ±.1° FINISH -		DWN: D. RINGLER 28JUL2005 CHK: J. WESTMAN 28JUL2005 APVD: S. FLICKINGER 28JUL2005 NAME: S. FLICKINGER PRODUCT SPEC: 108-1854 APPLICATION SPEC: 114-2160 WEIGHT: - CUSTOMER DRAWING: -		Tyco Electronics Corporation Harrisburg, PA 17105-3608 NAME: STACKED MODULAR JACK ASSEMBLY, 2X4 OFFSET, 8 POSN, RJ45 SHIELDED PANEL GROUND, NO LEDS, CAT 5 SIZE: A CAGE CODE: 00779 DRAWING NO: 6368077 SCALE: 4:1 SHEET: 1 OF 2 REV: C	
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LOC	DIST	REV	DATE	BY	APPV
AA	22				

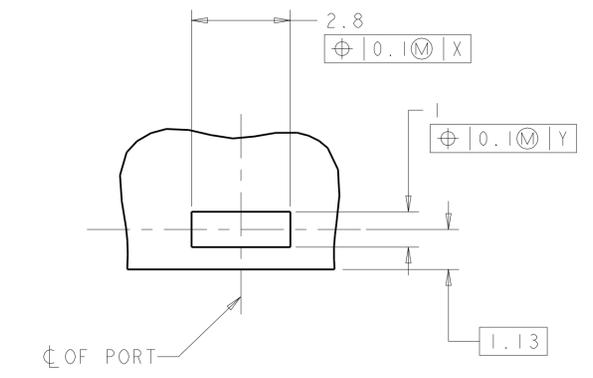
REVISIONS					
REV	DATE	DESCRIPTION	BY	APPV	DATE
-	-	SEE SHEET 1	-	-	-



RECOMMENDED PANEL CUT-OUT



PC BOARD LAYOUT
(COMPONENT SIDE)



DETAIL B
 THESE PLATED PADS ARE REQUIRED FOR
 PRODUCT WITH GROUNDING CLIPS
 SCALE 10:1
 4 PLACES

<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.</small>		DWN: D. RINGLER 28 JUL 2005 CHK: J. WESTMAN 28 JUL 2005 APV: S. FLICKINGER 28 JUL 2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608
DIMENSIONS: mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ±0.13 2 PLC ±0.13 3 PLC ± 4 PLC ± ANGLES ±1°	NAME: STACKED MODULAR JACK ASSEMBLY, 2X4 OFFSET, 8 POSN, RJ45 SHIELDED PANEL GROUND, NO LEDS, CAT 5 PRODUCT SPEC: 108-1854 APPLICATION SPEC: SIZE: 114-2160 WEIGHT: CUSTOMER DRAWING	SCALE: 4:1 SHEET: 2 OF 2 REV: C